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Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		HuaTian Technology (Xi An) Co.,Ltd							
Product Name:		TLSR8258F512ET48							
Weight(Unit):		129.534 mg						Date: 2023/10/17	
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	0.7120	Silicon	7440-21-3	0.7120	100.00%	0.55%	1000000
Die2	GD Die	SMIC BJ	0.2760	Silicon	7440-21-3	0.2760	100.00%	0.21%	1000000
Lead Frame	A194FH	Ningbo Kangqiang	67.9380					52.45%	
				Cu	7440-50-8	65.5602	96.50%	50.61%	965000
				Fe	7439-89-6	1.5626	2.30%	1.21%	23000
				P	7723-14-0	0.1019	0.15%	0.08%	1500
				Zn	7440-66-6	0.1359	0.20%	0.10%	2000
				Pb	7439-92-1	0.0034	0.01%	0.00%	50
				Ag	7440-22-4	0.5741	0.85%	0.44%	8450
DAF	ATB-120U	Henkel	0.0800	Modified Epoxy Resin	Proprietary	0.0528	66.0%	0.06%	660000
				Phenol, polymer with 3a,4,7,7a-tetrahydro-4,7-methano-1H-indene, glycidyl ether	119345-05-0	0.0184	23.0%	0.01%	230000
				Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	9003-36-5	0.0040	5.0%	0.00%	50000
				Aromatic polyamine	Proprietary	0.0040	5.0%	0.00%	50000
				Epoxy Resin	Proprietary	0.0008	1.0%	0.00%	10000
Epoxy	L1-403NCA	LEGEND	0.9570	Diethylene glycol monoethyl ether acetate	112-15-2	0.0957	10.00%	0.74%	100000
				Silica	15468-32-3	0.5742	60.00%	0.44%	600000
				Acylate resin	Proprietary	0.1436	15.00%	0.11%	150000
				Epoxy resin	Proprietary	0.1340	14.00%	0.10%	140000
				Peroxide	Proprietary	0.0096	1.00%	0.01%	10000
Wire	HS-ES5	Heesung	0.5630	Silver:Wire	7440-22-4	0.5348	94.9900%	0.43%	949900
				Gold	7440-57-5	0.0028	0.5000%	0.00%	5000
				Palladium	7440-05-3	0.0253	4.5000%	0.02%	45000
				Platinum	7440-6-4	0.0001	0.0100%	0.00%	100
Mold Compound	CEL-9220HF	SDMSZ	56.3330	Epoxy Resin 1	Trade secret	0.2817	0.50%	43%	5000
				Epoxy Resin 2	Trade secret	0.2817	0.50%	0.22%	5000
				Epoxy Resin 3	Trade secret	0.2817	0.50%	0.22%	5000
				Hardener	Trade secret	1.1267	2.00%	0.87%	20000
				Catalyst	Trade secret	0.0056	0.01%	0.00%	100
				Carbon black	1333-86-4	0.1127	0.20%	0.09%	2000
				Amorphous silica1	60676-86-0	50.0181	88.79%	38.61%	887900
				Amorphous silica2	7631-86-9	4.2250	7.50%	3.26%	75000
Plating	TIN	AISEN	2.6750	Tin	7440-31-5	2.6747	99.99%	2.07%	999900
				Others	Trade Secret	0.0003	0.01%	0.00%	100
Total			129.5340			129.5340	100%	1000000	